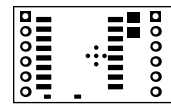
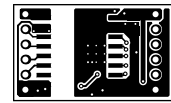


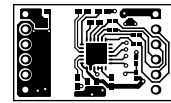
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-01230	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 2/8/2017 11:08:44 AM	TEXAS INSTRUMENTS	



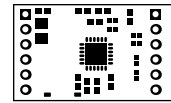
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-01230	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 2/8/2017 11:08:45 AM	TEXAS INSTRUMENTS	



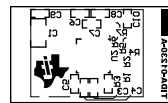
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-01230	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 2/8/2017 11:08:46 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-01230	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 2/8/2017 11:08:47 AM	TEXAS INSTRUMENTS	

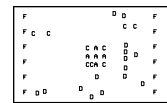


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-01230	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 2/8/2017 11:08:48 AM	TEXAS INSTRUMENTS	

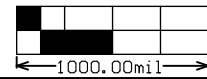
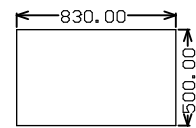


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-01230	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 2/8/2017 11:08:49 AM	TEXAS INSTRUMENTS	

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
A	5	7.87mil (0.200mm)	PTH	Round
C	9	10.00mil (0.254mm)	PTH	Round
D	15	12.00mil (0.305mm)	PTH	Round
F	12	31.50mil (0.800mm)	PTH	Round
	41 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-01230	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 2/8/2017	11:08:50 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #:TIDA-01230	REV: A	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Board Dimensions	GENERATED : 2/8/2017 11:08:51 AM	TEXAS INSTRUMENTS	

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